

JCS/1019
JC879 U.S. PTO
10/035247



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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10035247	FILING DATE 01/04/2002	CLASS 257	SUBCLASS 750	GAU 234 2844	EXAMINER WILSON
**APPLICANTS: Yi Sang Hyun; Kim Young Nam;					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED: REPUBLIC OF KOREA 2001-8480 02/20/2001					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO 262/009	
Verified and Acknowledged Examiners's initials					
TITLE : Semiconductor device having no cracks in one or more layers underlying a metal line layer and method of manufacturing the same					
U.S. DEPT. OF COMMERCE/PAT. & TRADEMARK OFFICE (Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims <input type="checkbox"/> Print Claim for O.G. <input type="checkbox"/>	
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
		Print Fig.	
<input type="checkbox"/> TERMINAL DISCLAIMER		Primary Examiner	
		PREPARED FOR ISSUE	
		Applicant Examiner	
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